Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L2	380	((underfill\$3 or encapsulant or encapsulat\$3) near2 (between or around or above or fill\$3 or space or open\$3) near5 (solder or ball or bump or interconnect or array) near5 ((organic near2 board) or substrate))	US-PGPU B; USPAT; EPO	OR	ON	2007/10/11 11:45
L3	3	1 and (((compressive or compression) near5 (force or pressure)) same ((thermal or temperature or heat\$3) near5 (coefficient or mismatch or expansion or "CTE")))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/10/11 11:43
L4	36	("2014524" "2774747" "3401126" "3429040" "4113981" "4442966" "5046415" "5056296" "5074947" "5196371" "5237130" "5539153" "5611140" "5667884" "5879761" "5924622"). PN. OR ("6399178"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2007/10/11 11:44
L5		((underfill\$3 or encapsulant or encapsulat\$3) near5 (organic near2 board) near5 ((thermal or temperature or heat\$3) near5 (coefficient or mismatch or expansion or "CTE")))	US-PGPU B; USPAT; EPO	OR	ON	2007/10/11 12:52

L9	26	daves-glenn\$.in.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM TDB	OR	ON	2007/10/11 12:49
L11	68	farooq-mukta\$.in.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T;	OR	ON	2007/10/11 12:51
			IBM_TDB			
L12	46	Pompeo-frank\$.in.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/10/11
L13	765	(9 or 10 or 11)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/10/11 12:52
L14	2	13 and ((underfill\$3 or encapsulant or encapsulat\$3) same (organic near2 board) same ((thermal or temperature or heat\$3) same (coefficient or mismatch or expansion or "CTE")))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON .	2007/10/11 12:53

L15	21	("5477082" "5530288" "5535526" "5598033" "5598036" "5636104" "5691041" "5729440" "6102710").PN. OR ("6333563").URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2007/10/11 12:53
L16	13	("4783722" "4897918" "5477933" "5641113" "5705858" "5931371" "6078123" "6177728" "6225206" "6333563"). PN. OR ("6697261"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2007/10/11 12:58
L17	58	("5007163" "5090609" "5147084" "5154341" "5234149" "5261593" "5275330" "5439162" "5535526" "5551627" "5611481" "5655703"). PN. OR ("5729440"). URPN.	US-PGPU B; USPAT; USOCR	OR	ON	2007/10/11 14:39
L20	41	(((underfill\$3 or encapsulant or encapsulat\$3) near5 (filler or particle or powder or particulate or mixture) near5 ((size or radius or radii or diameter or shape or form) near5 micron)) near5 (percentage or weight or volume))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/10/11 15:27

L23	53	("3808028" "4110364" "4188276" "4369302" "4534888" "4552690" "4604452" "4608434" "4627151" "4642321" "4700473" "4709008" "4713403" "4740343" "4740584" "4785075" "4839442" "4847233" "4855002" "4914814" "4946928" "4999136" "4999699" "5006673" "5011066" "5030308" "5036128" "5150195" "5186383" "5189077" "5216278" "5252355" "5395876" "53446118" "5489641" "5528157" "5536970" "5548884"	US-PGPU B; USPAT; USOCR	OR	ON	2007/10/11 15:17
		"5672297" "5744533"). PN. OR ("6121358"). URPN.				
L25	325	(((underfill\$3 or encapsulant or encapsulat\$3) near5 (filler or particle or powder or particulate) near5 ((size or radius or radii or diameter) near5 micron)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T;	OR	ON	2007/10/11 15:28
1.25	47	///~~~ ~~ ~~ ~~ ~~ ~~ ~~ ~~ ~~ ~~ ~~ ~~	IBM_TDB	OD	ON	2007/40/44
L35	17	(((gap or space or interval) same height same (mil or micron)) same (substrate near5 board))	US-PGPU B; USPAT	OR	ON	2007/10/11 16:32
L37	158	(((gap or space or interval or solder or bump or ball or pillar or spacer) same height same (mil or micron)) same (undefill or encapsulant or encapsulat\$3))	US-PGPU B; USPAT; EPO; DERWEN T	OR	ON	2007/10/11 16:36

L38	63	37 and ("CTE" or (coefficient adj thermal adj expansion))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T	OR	ON	2007/10/11 16:39
			T; IBM_TDB		•	

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C:\Documents and Settings\maboagye\My Documents\EAST\Workspaces\10711501 solder interconnect array with optimal mechanical int